



The European Institute for the PCB Community

# EIPC SPEeDNEWS

*The Weekly On-Line Newsletter*

*Issue 9 – March 2023*

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## NEWS FROM THE EIPC

### **Announcement**

EIPC Summer Conference Munich, Germany  
June 15 & 16, 2023

“Reading makes a full man; conference a ready man; and writing an exact man”.  
Essays Francis Bacon, 1625

One thing is for sure, an EIPC Conference covers all of those three requirements, so delegates invariably leave us having read, conferred and written to completion. Not to say dined as well!

Taking place in Munich on 15th & 16th June 2023, the highlight will be a visit to the World of BMW and their Museum at Olympia park, just outside the city on the 15th. But over those two days we plan to cover much other territory, as may be seen from our ‘wish list’ of topics that we would like to see covered. There is scope for everyone, so would you please be kind enough to allow us to share your knowledge and send us a summary as soon as you may.

Please may we have your abstract submission no later than March 31<sup>st</sup>.

You can download the Call for Papers and abstract submission form on [www.eipc.org](http://www.eipc.org)

Registration for the conference is now open: [www.eipc.org](http://www.eipc.org)



The European Institute for the PCB Community

Call for papers

EIPC Summer Conference Munich, Germany

June 15 & 16, 2023



**Bonus Programme: Visit to BMW World on Thursday June 15**

Presentations on the following topics can be included in the conference programme:

**Keynote / Trends**

- Business Outlook: Global Electronics Industry
- Automotive customer requirements for PCB supply chain
- Automotive, E-mobility, Energy, IoT, Medical Industrial Electronics, Aerospace, Avionics-G5
- Supply chain risk management

**Roadmapping for 2023 and beyond**

- Roadmap by market segments
- Technology Guidance through market needs
- Adapting processes, materials, chemistry, equipment to future technology needs
- Strategic Partnership and Planning for success through Networking

**Environmental responsibility**

- Sustainability development --Circular economy solutions through the whole supply chain- carbon footprint
- Green manufacturing

**New Technologies: Success through Evolution- or Disruptive Technologies?:**

- Process technology development SAP and full Additive Process
- Photonics: optical solutions in component and board level
- Laminate based Semiconductor Packaging
- Embedded technology: Passives, actives, Power modules
- Nanotechnology and Printed electronics: 3D Electronics /conductive pattern/dielectric layers
- Material Technology: Laminate technologies - Coating technologies
- Ni free surface finishes
- New technology: Innovations and Invention

**Equipment and process evolution to meet Technology Challenges and Smart manufacturing**

- Equipment and process capabilities improving PCB conductor features management and process tolerances
- Etching and plating technology for improved conductor control and copper thickness tolerances
- Industry 4.0, Automation and AI in PCB manufacturing
- Imaging and Printing Technology
- Laser, Mechanical drilling

- ML-Pressing for high frequency product, improving variation

- Thermal PCB solutions, Metal Core PCBs

**Materials, Reliability and Traceability requirements by Application**

- Material solution for Automotive industry
- Responsibility and Standards for Product Reliability and Safety
- In-house process control and conformation Testing
- Material and finished product Safety and Testing
- Advanced supply chain and Third party Testing

**Measurement methodology**

- Copper: thickness and roughness -How to measure and verify copper roughness against new requirements
- Standardization and methodology
- Measurement automation - In production controls
- High frequency measurement and automation
- Tools for Testing and ensuring product safety and reliability



Please visit  
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### NEWS FROM AUSTRIA

#### **AT&S already positions itself for the financial year 2026/27**

*Customer diversification successfully initiated*

*Revenue growth of €1.8billion in 2022/23e to €3.5billion in 2026/27e*

*Ready for challenging market environment*

Given the current market environment, AT&S has adapted its pace of growth to the market conditions and postponed its medium-term goals by a year to the 2026/27 financial year. “While the current weakness of the market in the area of IC substrates affects the speed of our growth, it does not change anything about the long-term perspective of our markets and our positioning,” says CEO Andreas Gerstenmayer. “On the contrary, we will use this challenging time to emerge stronger and continue to drive our strategy with a broader customer portfolio,” Gerstenmayer comments on the company’s perspective. “Initially, this will, however, require consequent adjustments to our cost structures,” he concedes.

**Customer diversification successfully initiated**

As part of its diversification strategy, AT&S has already succeeded in winning additional IC substrate customers. Therefore, the R&D centre in Leoben, which is currently under construction, will be expanded to include real series production, supported by financing contributions of the new customers. These customers operate in the computing/data processing business and have a high need for IC substrates; they use these to offer energy-efficient processors, among other things.

In addition to the diversification in the area of IC substrates, the company also won major new customers in the PCB business and significantly increased profitability. This shows that a broad, high-quality portfolio pays off.

Revenue growth of €1.8billion in 2022/23e to €3.5billion in 2026/27e

The outlook for 2025/26, which AT&S presented in November 2021, was based on a completely different market environment with high growth forecast for IC substrates. The Ukraine conflict and its impact on the energy market, growing tensions between the USA and China as well as the general economic slowdown, coupled with rising inflation, have had a significant negative effect on market conditions after the end of the COVID pandemic. The extreme increase in PC and notebook sales as a result of mandatory remote working during the pandemic led to a saturation in this segment and consequently market weakness coupled with high inventories.

As a result of the changes in the market and the reduced growth momentum, AT&S had to adapt its projects and projections. The medium-term goals were consequently postponed by a year. AT&S expects to generate revenue of approximately € 3.5 billion in 2026/27 and anticipates an EBITDA margin of 27 to 32%. This corresponds to a compound annual growth rate for revenue of 17% (2022/23e: € 1.8 billion) and a significant increase in profitability.

Ready for a challenging market environment

In the markets for IC substrates, demand for notebooks is expected to be lower in 2023 than in 2022. The negative impact on the supplier chain is further intensified by high inventories. According to current forecasts, this will affect the first half of 2023 in particular; towards the end of the year, demand is expected to recover. The demand for IC substrates for servers will benefit from the technology shift towards heterogeneous integration[1].

In order to mitigate the resulting effects, such as pressure on prices and inflation, AT&S has initiated comprehensive cost optimisation programmes. These programmes focus on expanding the scope for the ongoing improvement measures and on accelerating their implementation. AT&S had already announced sustainable cost optimisations in February, predominantly based on measures to increase productivity and material use as well as optimisations in purchasing. Against the backdrop of growing market challenges, AT&S has intensified these programmes. Compared to the financial year 2022/23 cost savings totalling € 440 million are expected for the following two years.

In addition, the investment programmes will be analysed depending to the respective expected demand and adapted to the respective market situation. In the 2022/23 financial year AT&S invested CAPEX of approximately € 600 million in the location in Chongqing, China. The plant in Leoben, Austria, is being completed for the new customers and the first machines are already being installed. In Kulim, Malaysia, € 340 million was invested in the 2022/23

financial year. One of the two plants in Kulim is currently being finalised; the first machines have already been installed. Production is expected to start in 2024 as planned. The second plant in Kulim will be completed regarding the building envelope, for which considerable costs will still be incurred; however, the timing of the procurement and installation of the infrastructure and production equipment depends on how the market and the situation of a relevant customer develop. As a result, the investment volume for the 2023/24 and 2024/25 financial years will be reduced by a total of € 450 million compared with the original plan – despite an increase in investment requirements in Leoben. In 2021, AT&S had announced investments totalling € 2.2 billion for the locations in Kulim and Leoben; currently the company is planning total investments of € 1.8 billion in the medium term.

AT & S Austria Technologie & Systemtechnik Aktiengesellschaft – Advanced Technologies & Solutions

AT&S is a globally leading manufacturer of high-end printed circuit boards and IC substrates. AT&S industrialises leading-edge technologies for its core business segments Mobile Devices & Substrates, Automotive, Industrial and Medical. AT&S has a global presence with production sites in Austria (Leoben, Fehring) and plants in India (Nanjangud), China (Shanghai, Chongqing) and Korea (Ansan near Seoul). A new high-end production site for IC substrates is currently being established in Kulim, Malaysia. The company employs roughly 15,000 people.



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## NEWS FROM FINLAND

### Notice of the Annual General Meeting of Aspocomp Group Plc

Notice is given to the shareholders of Aspocomp Group Plc. to the Annual General Meeting to be held on Thursday, April 20, 2023 at 10 a.m. (EET), address Keilaranta 1, 1st floor Auditorium, Espoo, Finland. The reception of persons who have registered for the meeting will commence at 9.30 a.m. (EET).

#### A. MATTERS ON THE AGENDA OF THE ANNUAL GENERAL MEETING

At the Annual General Meeting, the following matters will be handled:

1. Opening of the meeting
2. Calling the meeting to order
3. Election of persons to scrutinize the minutes and to supervise the counting of votes
4. Recording the legality of the meeting
5. Recording the attendance at the meeting and adoption of the list of votes
6. Presentation of the annual accounts, the consolidated annual accounts, the report of the Board of Directors and the auditor's report for the year 2022

#### Review by the CEO

The annual report of the company for the year 2022, including the company's annual accounts, the consolidated annual accounts and the report of the Board of Directors as well as the auditor's report shall be available on the company's website at [www.aspocomp.com/reports](http://www.aspocomp.com/reports) as of March 28, 2023.

7. Adoption of the annual accounts and the consolidated annual accounts
8. Resolution on the use of the profit shown on the balance sheet and payment of dividend

The Board of Directors proposes to the Annual General Meeting, that a dividend of EUR 0.21 per share be paid. The dividend would be paid to

shareholders registered in the Register of Shareholders maintained by Euroclear Finland Ltd on the record date of the dividend distribution, April 24, 2023. The Board of Directors proposes that the dividend will be paid on May 2, 2023.

9. Resolution on the discharge from liability of the members of the Board of Directors and the CEO

10. Presentation of the remuneration report 2022 for company's governing bodies

The Board of Directors proposes to the Annual General Meeting that it would approve the company's remuneration report for governing bodies 2022. The resolution concerning approval of the remuneration report is advisory in nature.

The remuneration report will be available on the company's website [www.aspocomp.com/agm](http://www.aspocomp.com/agm) as of March 16, 2023

11. Resolution on the remuneration of the members of the Board of Directors

The Shareholders' Nomination Board proposes to the Annual General Meeting that the amount of remuneration payable to the Board of Directors remain the same as in the ending term and that Board Members be thus compensated as follows: EUR 30,000 for the chairman of the Board of Directors, EUR 20,000 for the vice chairman, and EUR 15,000 for each of the other members in remuneration for their term of office. The Nomination Board further proposes that EUR 1,000 be paid as remuneration per meeting to the chairman and that the other members be paid EUR 500 per meeting of the Board and its committees. The Nomination Board also proposes that the members of the Board of Directors be reimbursed for reasonable travel costs.

12. Resolution on the number of members of the Board of Directors

The Shareholders' Nomination Board proposes to the Annual General Meeting that four (4) members be elected to the Board of Directors.

13. Election of members of the Board of Directors

The Shareholders' Nomination Board proposes to the Annual General Meeting that the current members of the Board of Directors Ms. Päivi Marttila, Ms. Kaarina Muurinen, Mr. Jukka Huuskonen and Mr. Anssi Korhonen be re-elected as members to the Board of Directors. In accordance with the Articles of Association of the company, the term of office of the members of the Board of Directors ends at the closing of the next Annual General Meeting following the election.

The said director nominees have given their consents to the election. The nominees' personal details are available on the company's website [www.aspocomp.com](http://www.aspocomp.com).

In accordance with the Articles of Association the Board of Directors elects its chairman from among its members. The Nomination Board proposes to the inaugural meeting of the Board of Directors to be held after the Annual General Meeting that Ms. Päivi Marttila is re-elected as chairman of the Board of Directors.

The Nomination Board has assessed the director nominees' independence against the independence criteria of the Finnish Corporate Governance Code. According to the evaluation carried out by the Nomination Board, all director nominees are independent of the company's significant shareholders. The Nomination Board has also assessed that all nominees are independent of the company.

14. Resolution on the remuneration of the auditor

The Board of Directors proposes to the Annual General Meeting that the auditor's fees be paid according to the auditor's invoice.

15. Election of auditor

The Board of Directors proposes to the Annual General Meeting that PricewaterhouseCoopers Oy, Authorized Public Accountants be re-elected as the company's auditor. PricewaterhouseCoopers Oy has notified that Mr. Tuukka Kiuru, Authorized Public Accountant, will act as the principal auditor. In accordance with the Articles of Association of the company, the term of office of the auditor ends at the closing of the next Annual General Meeting following the election.

16. Authorizing the Board of Directors to decide on share issues as well as the issue of options and other special rights

The Board of Directors proposes to the Annual General Meeting that the Board of Directors be authorized to, in one or several instalments, decide on the issuance of shares and the issuance of options and other special rights entitling to shares referred to in Chapter 10 Section 1 of the Finnish Limited Liability Companies Act as follows:

The number of shares to be issued based on the authorization may in total amount to a maximum of 681,144 shares. The Board of Directors decides on all the terms and conditions of the issuances of shares and of options and other special rights entitling to shares. The authorization concerns both the issuance of new shares as well as own shares possibly held by the company.

The issuance of shares and of options and other special rights entitling to shares referred to in Chapter 10 Section 1 of the Finnish Limited Liability Companies Act may be carried out in deviation from the shareholders' preemptive rights (directed issue).

The authorization cancels the authorization given by the General Meeting on April 26, 2022, to decide on the issuance of shares as well as the issuance of special rights entitling to shares.

The authorization is valid until June 30, 2024.

#### 17. Amendment of the Articles of Association

The Board of Directors proposes that the Annual General Meeting would decide to amend the company's Articles of Association to enable convening a General Meeting as a virtual meeting without a meeting venue as an alternative to a customary general meeting or a hybrid meeting. The Finnish Companies Act requires that shareholders can exercise their full rights in virtual meetings, with equal rights to those in customary in-person General Meetings. Pursuant to the proposal of the Board of Directors, 9 § of the company's Articles of Association would be amended to read as follows:

"9 § The General Meeting shall be held in Helsinki or Espoo. The Board may decide that the General Meeting is arranged without a meeting venue in a manner where shareholders exercise their full decision-making powers in real time during the General Meeting using telecommunications and technical means (virtual meeting).

In order to exercise his right to speak and vote at the General Meeting, a shareholder must register in the manner specified in the invitation to the meeting. The closing date for registration shall be no sooner than ten days before the meeting."

#### 18. Closing of the meeting

##### B. DOCUMENTS OF THE ANNUAL GENERAL MEETING

The aforementioned proposals of the Shareholders' Nomination Board and the Board of Directors relating to the agenda of the Annual General Meeting, this notice and the company's Remuneration Report for Governing Bodies 2022 will be available on the company's website at [www.aspocomp.com/agm](http://www.aspocomp.com/agm) starting from March 16, 2023. The annual report of the company for the year 2022, including the company's annual accounts, the consolidated annual accounts and the report of the Board of Directors as well as the auditor's report shall be available on the company's website at [www.aspocomp.com/reports](http://www.aspocomp.com/reports) as of March 28, 2023. The proposals for decisions and the other above-mentioned documents are also available at the

meeting. Copies of these documents and of this notice will be sent to shareholders upon request

The minutes of the Annual General Meeting will be available at [www.aspocomp.com/agm](http://www.aspocomp.com/agm) no later than May 4, 2023.



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### NEWS FROM NORWAY

#### **CONFIDEE welcomes Craig Haywood to the team**



*Oslo, Norway - CONFIDEE is proud to announce the appointment of Craig Haywood as Operations Manager. "With nearly three decades of experience in PCB manufacturing, Craig brings a wealth of knowledge and expertise to our team", says CEO Vidar Olsen.*

CONFIDEE's foundation, is transparent and long-term partnerships with our partners. "As an industry veteran with extensive experience in PCB technology, Craig will ensure that we can further build close and Personal relationships with our partners. With Craig onboard, we are taking partnerships to the next level", says Olsen.

The combination of an advanced IT system and highly experienced and skilled human resources, create a powerful synergy. "We have worked tirelessly to create, ID, our compliance technology software, streamlining and digitalizing the PCB supply chain, protecting our partners data. By leveraging compliance technology and combining it with human resources like Craig, we are taking a small step in increasing our team, but a significant move towards improving the industry" added Olsen.

Craig Haywood is equally enthusiastic about joining the team.

"I am thrilled to be part of a company that has a strong commitment to learn, build and share competence and technology. They have a clear focus on developing solutions which create value propositions for their partners and

finding new ways to make the work-day easier and more transparent", he says.

"For me it's all about the people, the culture and respect in relation to how you do business and how you treat people, always with a goal to do better, and make a difference as a person, friend, colleague and partner", Haywood concludes.

With Craig Haywood's appointment as Operations Manager, the Operations department consists of Asle Høibybråten, Craig Haywood and Yik Chuang Tang and more people are on the way.

"We are ready to take industry to the next level, being agile, transparent, and humble to those who have placed their trust in CONFIDEE," says Olsen.



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## NEWS FROM THE UK

### ICT SEMINAR MERIDIEN

Pete Starkey's excellent coverage of this event may now be seen on the following link:

<http://pcb.iconnect007.com/index.php/article/135592/ict-seminar-2023-review-energy-thermals-and-assistive-technology/135595/?skin=pcb>

### Silicon Chip Industry Awareness Workshop Seminar

#### **Unlock Your Potential Today!**

Whether you're a non-technologist struggling with the jargon or a specialist looking to understand the overall industry structure, this workshop is for you. Join us on Tue 28 March 2023, 9:30am to 4:00pm at the Holiday Inn in Kensington, London, England.

Gain a competitive edge in the Semiconductor Industry by learning how the IC industry works from the science that enables silicon chips to be made from sand to the market fundamentals that drive applications and economics. Experience the industry through Listen, Discuss, See, Touch, and Learn activities and enjoy improved job satisfaction and operational efficiency.

Priced at just UK£695 plus 20 percent UK VAT per delegate, the fee includes copies of presentation materials, coffee breaks and lunch. Workshops can also be held in-house for your added convenience and flexibility. Only 10 spots available, so don't wait – Secure Your Spot Today at:  
<https://www.futurehorizons.com/page/12/silicon-chip-training>

### **Past Attendee Comments**

- \* As a non-technologist, it was very beneficial to have these issues so clearly explained
- \* The seminar provided a good basis to understanding the industry
- \* It was GREAT! I can't remember a day of a similar density
- \* I finally understand how to recognize products & their use in technology
- \* This has helped me structure my thoughts & plans for the company
- \* It gave me deeper insight into the industry in a way difficult to obtain anywhere else
- \* This will be very useful when involved in our core business development discussions

Please pass to your HR Department or a colleague if already attended or not suitable for you.

Sincerely

Malcolm Penn, Chairman & CEO

Blakes Green Cottage, Sevenoaks, Kent TN15 0LQ, England

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Registered Company: 4380991

Follow us on Twitter @Future\_Horizons and join our Linked In Group

(<http://uk.linkedin.com/in/malcolmpenn>) and receive regular industry news, information and comments.

### **British Semiconductor Bosses Threaten To Move Overseas As U.S. And EU Splurge On Chips**

The U.K.'s semiconductor industry is crying out for financial support from the government, with insiders warning the country risks losing its microchip firms to the U.S. and other countries if it doesn't act soon. Prime Minister Rishi Sunak's government is yet to announce a strategy outlining U.K. efforts to support the chip industry. And semiconductor bosses in the country are growing frustrated.

Pragmatic Semiconductor, a Cambridge, England-based startup that produces non-silicon chips, warned it may be forced to relocate overseas if the government doesn't issue a plan for the industry soon. "It has to make economic sense for companies like ours to continue to operate and manufacture here, and if there are greater potential economic benefits and

governmental support packages abroad, then relocation is the only sensible business decision,” Scott White, CEO of Pragmatic Semiconductor, told CNBC.

Britain is an understated player in the global chip market, specializing in design, intellectual property, research and fabrication of compound semiconductors. It is also home to one of the most coveted semiconductor-related assets in the form of chip designer Arm. Based in Cambridge, Arm-licensed chips are used in roughly 95% of the world’s smartphones.

## **UK manufacturers stave off recession despite inflationary pressures**

Britain’s manufacturers have seen a rebound in activity in the first quarter of the year, staving off fears of a recession in the sector, although strong inflationary pressures are still having a major impact.

A report from Make UK shows a marked improvement in the sector compared to the final quarter of 2022. The figures echo gradual improvements seen in other data regarding the state of the UK and European manufacturing sector.

The improvement is being driven by strong demand in the **electronics** and mechanical equipment sectors, with the balance of orders in the electronics sector extremely strong, the Manufacturing Outlook report said.

This could be due to several factors, including companies investing in digitalisation and extra capacity to counter labour shortages or, to take advantage of the final period of the super deduction scheme before it ends this month. Demand for electronics goods is especially strong from overseas, in particular the EU.

The report also showed that the sector is now in its ninth consecutive quarter of elevated price metrics, where manufacturers have consistently raised both their UK prices and export prices “far beyond” the norm.

Fhaheen Khan, a senior economist at Make UK, said: “Manufacturers have seen a rebound at the start of the year as conditions have improved in their major markets and, business confidence has improved. However, one swallow doesn’t make a summer and it is far too early to say the worst has passed given the significant challenges the economy faces.”

In October, the Office for National Statistics said that the number of UK manufacturing businesses shrank by 10 per cent in 2021, while turnover also fell by 9.2 per cent.

The decrease in the number of companies in the sector was attributed to a decreasing number of orders which saw manufacturers cut back on their production.

Richard Austin, manufacturing head at accountancy firm BDO, said: “The results of our research with Make UK illuminates that, despite glimmers of good news such as strong demand for electronics and mechanical equipment, inflationary pressures are still very evident for UK manufacturers with increased costs still being passed on.

“The data shows conflicting upward and downward indicators – potentially an industry at a crossroads. It will be fascinating to see which path will be followed over the coming months.”

[eandt.theiet.org](http://eandt.theiet.org)



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## NEWS FROM THAILAND



*Hauke Otten, STARTEAM GLOBAL COO, leading the introduction of the workshop*

### **An insight into STARTEAM GLOBAL's Smart Manufacturing factory in Thailand.**

As announced at the end of 2022, STARTEAM GLOBAL is well on its way to open the doors of our Thailand factory before the end of the year. For this to happen, rigorous planning is needed and has already started. Through the process so far, it has been decided to run the new factory under a Smart Manufacturing system.

Smart Manufacturing systems are fully integrated, collaborative manufacturing systems that respond to changes in demands or conditions in the factory in real time. While this is the common definition which can be found, we wanted to get a deeper understanding of the subject, as well as

define what Smart Manufacturing means to us. To achieve the best results for this, we hosted a Smart Manufacturing workshop on-site of our Thailand factory. Around twenty of our STG experts participated in the workshop, alongside our partners that will help us in the set-up of our factory. The workshop lasted three days with all the time spent there being dedicated to find a clear Smart Manufacturing system that will perfectly suit our needs. One of the crucial aspects we wanted to define from the beginning was what the word 'smart' means to us.

Our definition of 'smart' is:

*"To decide and act rationally based on the information given at a certain point in time and continuously improve on this."*

When looking at behaving smart from the angle of the information that is available to one, it makes it clear that to give yourself the best chances of acting smart is done by having the best and most reliable information available. The information needed to improve processes in a factory is the production data, the core of our Smart Manufacturing system. The aim is to collect as much data from our production as possible, which will then be stored in a cloud. The data collection will be facilitated by a Manufacturing Execution System, which will allow us to view live data from any process in our plant. Each process will get its own data model to achieve the most accurate results, which is important as accurate data will lead to accurate interpretations. By connecting the machines and operators to a closer level, more efficient production plans can be made to reduce things such as cost or waste.

With a system like this in place, we can focus on long term goals in our production, one of these being product traceability, which will allow full transparency towards all our stakeholders. Another advantage this gives us the ability to predict matters such as machine maintenance and the quality of the board, which allows us to be as flexible as possible.

All these features will allow us to progress to a leaner manufacturing style, thus being able to eliminate unnecessary waste such as transportation, time, defects and overproduction. This will be a further way we continue to offset the size of our carbon footprint.

All these features and eventual results are what convinced us of Smart Manufacturing. We are always looking to be more efficient in our production, and this data analysis driven way of planning the production will allow us to do just that.

*STARTEAM GLOBAL is a globally recognised printed circuit board manufacturer with 30 years of experience in the industry. We Exceed Manufacturing by*

*delighting our customers with sustainability in everything we do. Our factory in Sichuan province, China manufactures PCBs to the highest quality and reliability standards, including automotive, medical and railway safety requirements, supported by our engineering and quality experts. STARTEAM GLOBAL strives to deliver the most competitive premium products and supply solutions to satisfy all your PCB requirements. Visit us on [www.starteam.global](http://www.starteam.global) for further information.*



Issue 9 - March 2023

## NEWS FROM THE IPC

### **IPC Announces New Thought Leaders Program Experts**

*Program delivers enhanced awareness and insights on electronics industry trends*

**BANNOCKBURN, Ill., USA, March 15, 2023** — IPC has revamped its Thought Leaders Program (TLP) an initiative designed to “mine” key industry experts’ insight and knowledge on issues driving change within the electronics industry.

Five experts have been selected to generate ideas and insights in five areas: education and workforce; technology and innovation; the economy; key markets; and environment, health, and safety. The TLP is chaired by [Mike Carano](#), IPC consultant, and a member of IPC’s Hall of Fame.

New TLP member are:

- [Peter Bigelow](#), President and CEO, IMI Incorporated
- [Matt Holzmann](#), President, CGI Americas
- [Stanton Rak](#), Principal, SF Rak Company
- [Stephen Sweeney](#), Program Manager, Materials and Environmental Management, IBM
- [Hiroyuki Watanabe](#), Executive Director, Global Security, NEC Corporation

The Thought Leaders’ responsibilities will include providing publishable material in their subject areas; flagging opportunities for IPC engagement; and participating in quarterly roundtable discussions. Each expert is expected to fulfill at least one 12-month term, during which quarterly contributions will be expected.

“I’m honored to work with such a diverse and august group of experts,” said Mike Carano. “The program is drawing on individuals who are leaders within the electronics manufacturing industry and who also have insights into

market research, trends, cybersecurity, high-tech production, emerging technologies, sustainability, business management, materials science and consulting. Our industry rapidly changes, and these experts have been assembled to provide guidance and solutions to lead and influence change toward building electronics better.”

For more information on the Thought Leaders Program, visit [www.ipc.org/advocacy/ipc-thought-leaders-program](http://www.ipc.org/advocacy/ipc-thought-leaders-program).



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## International Diary

### 2023

#### **21<sup>st</sup> EIPC Technical Snapshot Webinar**

19 April

Registrations via [www.eipc.org](http://www.eipc.org)

#### **EIPC @ SMTconnect**

9-11 May

Nuremberg, Germany

#### **EIPC Summer Conference**

Visit BMW World

15 & 16 June

Munich, Germany

#### **22<sup>nd</sup> EIPC Technical Snapshot Webinar**

Registrations via [www.eipc.org](http://www.eipc.org)

September

#### **23<sup>rd</sup> EIPC Technical Snapshot Webinar**

Registrations via [www.eipc.org](http://www.eipc.org)

October

#### **EIPC @ Productronica 2023**

14-17 November

München, Germany

#### **24<sup>th</sup> EIPC Technical Snapshot Webinar**

Registrations via [www.eipc.org](http://www.eipc.org)

December